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Assignee: SEH
Field: WAFER POLISHING
Description: Mounting method
Note: The original patent application is in MEMC's Patent Library. A copy is available upon request; contact aroos@memc.com.
IMPORTANT NOTE: To check for English equivalents, see Patent Family and Patent Details in the abstract below.

Patent:

Translation:

Abstract:

JP 10029156 A
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XRXPX Acc No: N98-129680

Polishing method for semiconductor wafer used in semiconductor IC manufacture - involves elastic deformation of shape of support plate following shape of abrasive cloth on fixed board after applying predetermined load on support plate, when sanding semiconductor wafer mounted on support plate

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Number of Countries: 001 **Number of Patents:** 001

Patent Family:

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JP 10029156 A 19980203 JP 96183818 A 19960712 B24B-037/04 199815
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Priority Applications (No Type Date): JP 96183818 A 19960712

Patent Details:

Patent Kind Lan Pg Filing Notes Application Patent
 JP 10029156 A 5

Abstract (Basic): JP 10029156 A

The method involves placing semiconductor wafers (1) on the mounting surface of a support plate (2). The semiconductor wafer on the support plate is pushed against the surface of an abrasive cloth (6) mounted on a fixed board (4). A semiconductor wafer retainer, on which the wafer holding surface is formed, projects from the other portion of the support plate.

When sanding the semiconductor wafer using the reaction force effected from the semiconductor wafer to the support plate, the shape of the support plate is elastically deformed following the shape of the abrasive cloth surface on the fixed board after applying a predetermined load (3) on the back of the support plate. The sanding of the semiconductor wafer is performed by maintaining the wafer on the

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wafer holding surface of the support plate while rotating the fixed board during the rotation of a rotary shaft (5).

ADVANTAGE - Obtains uniform polishing allowance. Lightweight semiconductor wafer with suitable flatness can be manufactured at low cost.

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Title Terms: POLISH; METHOD; SEMICONDUCTOR; WAFER; SEMICONDUCTOR; IC; MANUFACTURE; ELASTIC; DEFORM; SHAPE; SUPPORT; PLATE; FOLLOW; SHAPE; ABRASION; CLOTH; FIX; BOARD; AFTER; APPLY; PREDETERMINED; LOAD; SUPPORT; PLATE; SAND; SEMICONDUCTOR; WAFER; MOUNT; SUPPORT; PLATE

Index Terms/Additional Words: INTEGRATED; CIRCUIT

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